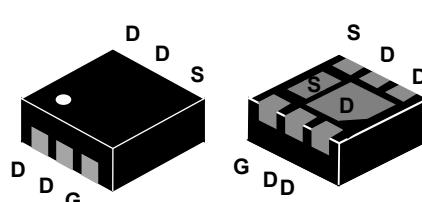
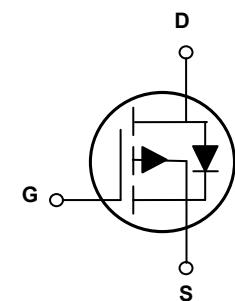


Main Product Characteristics

BV _{DSS}	-20V
R _{DS(ON)}	21mΩ (Max.)
I _D	-10A



DFN2x2-6L 2EP



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFB2121 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _{GS}	±12	V
Drain Current-Continuous (T _C =25°C)	I _D	-10	A
Drain Current-Continuous (T _C =100°C)		-7	
Drain Current-Pulsed ¹	I _{DM}	-40	A
Single Pulse Avalanche Energy ²	E _{AS}	20	mJ
Single Pulse Avalanche Current ²	I _{AS}	-8.8	A
Power Dissipation (T _C =25°C)	P _D	1.9	W
Power Dissipation-Derate above 25°C		0.015	W/°C
Thermal Resistance, Junction-to-Case	R _{θJC}	66	°C/W
Operating Junction Temperature Range	T _J	-55 To +150	°C
Storage Temperature Range	T _{STG}	-55 To +150	°C

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-20	-	-	V
BV_{DSS} Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C , $I_{\text{D}}=-1\text{mA}$	-	-0.01	-	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	-1	μA
		$V_{\text{DS}}=-16\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	-	-	-10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 10\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	μA
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-5\text{A}$	-	16	21	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}, I_{\text{D}}=-4\text{A}$	-	21	29	$\text{m}\Omega$
		$V_{\text{GS}}=-1.8\text{V}, I_{\text{D}}=-3\text{A}$	-	30	41	$\text{m}\Omega$
Forward Transconductance	g_{fs}	$V_{\text{DS}}=-10\text{V}, I_{\text{S}}=-5\text{A}$	-	15	-	S
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=-250\mu\text{A}$	-0.5	-0.7	-1	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta V_{\text{GS}(\text{th})}$		-	3	-	$\text{mV}/^\circ\text{C}$
Dynamic and Switching Characteristics						
Total Gate Charge ^{2,3}	Q_g	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-5\text{A}$ $V_{\text{GS}}=-4.5\text{V}$	-	15	-	nC
Gate-Source Charge ^{2,3}	Q_{gs}		-	2.6	-	
Gate-to-Drain Charge ^{2,3}	Q_{gd}		-	4.3	-	
Turn-On Delay Time ^{2,3}	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-10\text{V}, R_{\text{G}}=3\Omega$ $V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-5\text{A}$	-	9	-	nS
Rise Time ^{2,3}	t_r		-	28	-	
Turn-Off Delay Time ^{2,3}	$t_{\text{d}(\text{off})}$		-	24	-	
Fall Time ^{2,3}	t_f		-	7	-	
Input Capacitance	C_{iss}	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	1980	-	pF
Output Capacitance	C_{oss}		-	242	-	
Reverse Transfer Capacitance	C_{rss}		-	126	-	
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$V_G=V_D=0\text{V}$, Force Current	-	-	-10	A
Pulsed Source Current	I_{SM}		-	-	-40	A
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-1\text{A}$ $T_J=25^\circ\text{C}$	-	-	-1	V

Notes:

- Repetitive rating: Pulsed width limited by maximum junction temperature.
- $V_{\text{DD}}=-20\text{V}, V_{\text{GS}}=-10\text{V}, L=0.5\text{mH}, R_{\text{G}}=25\Omega$, starting $T_J=25^\circ\text{C}$.
- Pulse test: pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.

Typical Electrical and Thermal Characteristic Curves

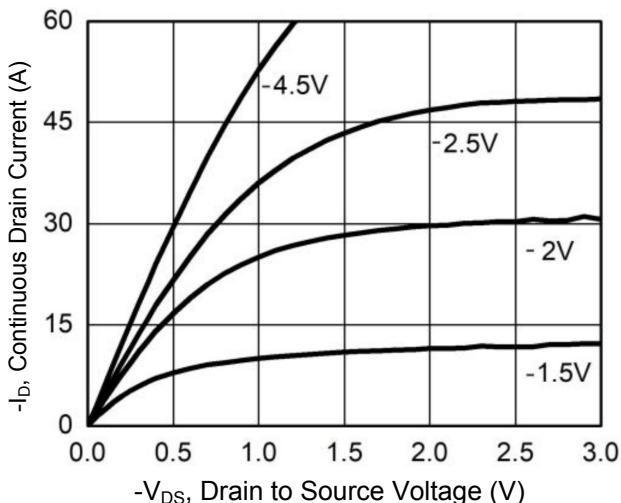


Figure 1. Output Characteristics

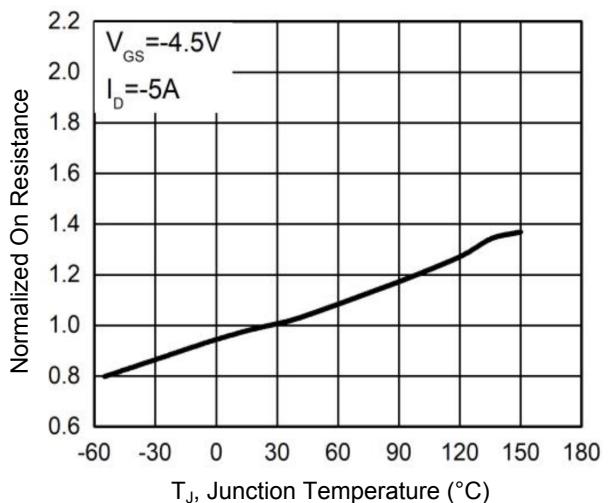


Figure 2. Normalized $R_{DS(on)}$ vs. T_J

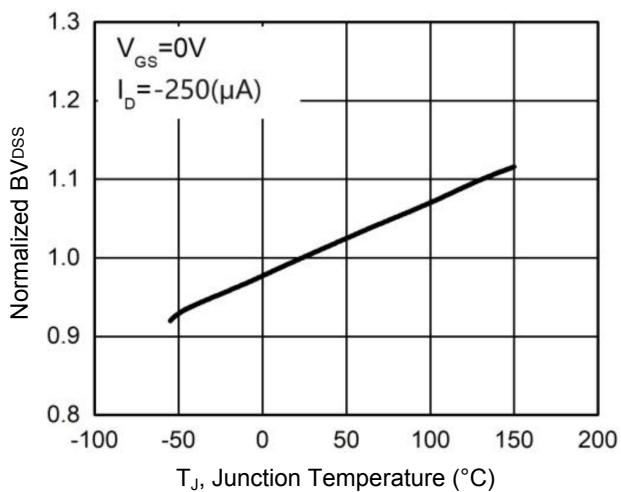


Figure 3. Normalized BV_{DSS} vs. T_J

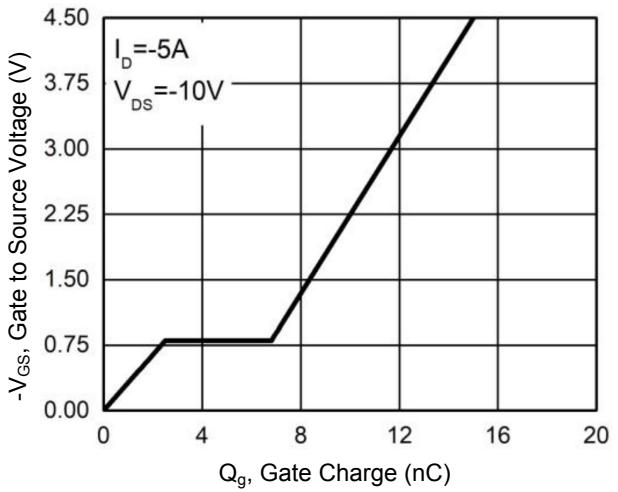


Figure 4. Gate Charge Waveform

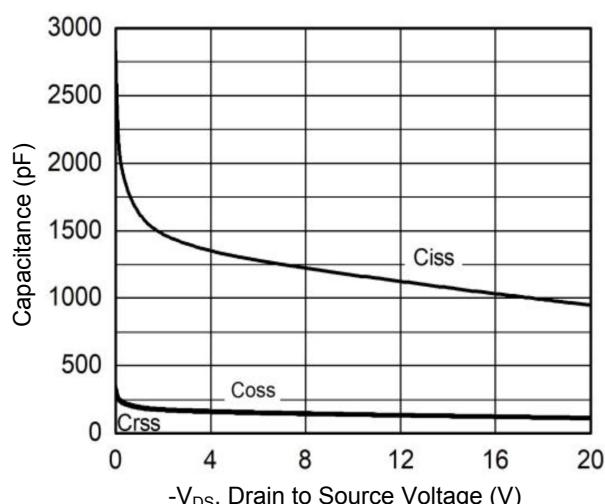


Figure 5. Capacitance Characteristics

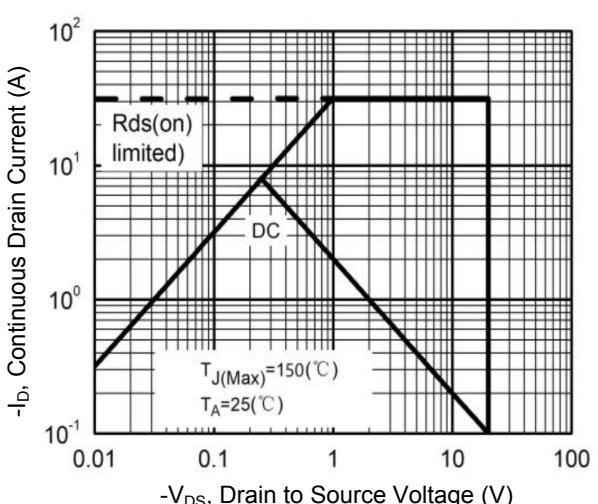
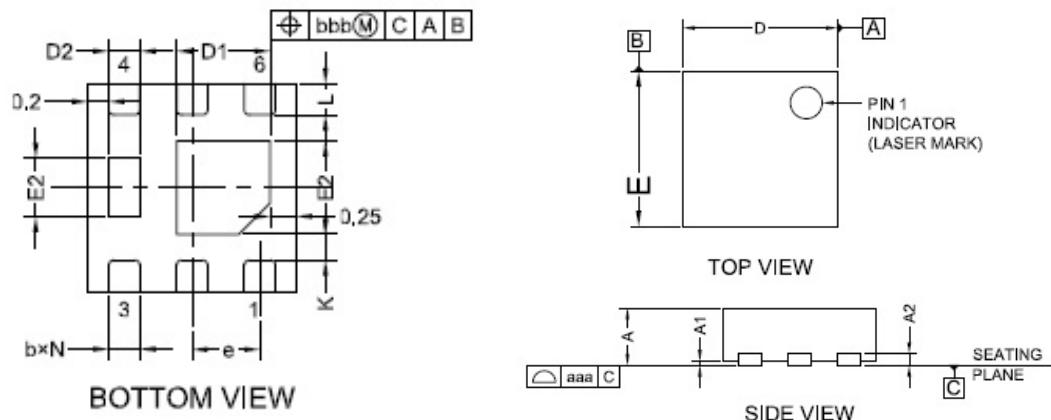


Figure 6. Maximum Safe Operation Area

Package Outline Dimensions (DFN2x2-6L 2EP)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.500	0.600	0.020	0.024
A1	0.000	0.005	0.000	0.000
A2	0.152 REF		0.006 REF	
b	0.250	0.350	0.010	0.014
D	1.950	2.050	0.077	0.081
D1	0.800	1.000	0.031	0.039
D2	0.250	0.350	0.010	0.014
E	1.950	2.050	0.077	0.081
E1	0.800	1.000	0.031	0.039
E2	0.460	0.660	0.018	0.026
e	0.650 BSC		0.026 BSC	
L	0.250	0.350	0.010	0.014
J	0.400 BSC		0.016 BSC	
K	0.200 MIN		0.008 MIN	
N	6.000		0.236	
aaa	0.080		0.003	
bbb	0.100		0.004	

Order Information

Device	Package	Marking	Quantity	Carrier
GSFB2121	DFN2x2-6L 2EP	B2121	3,000pcs / Reel	Tape & Reel